# Onsemi

MARKING

# TinyLogic UHS Dual Buffer with 3-STATE Outputs **NC7WZ241**

#### Description

The NC7WZ241 is a Dual Non-Inverting Buffer with 3-STATE outputs. The output enable circuitry is organized as active LOW for one buffer and active HIGH for the other buffer, thus facilitating transceiver operation.

The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad V<sub>CC</sub> operating range. The device is specified to operate over the 1.65 V to 5.5 V V<sub>CC</sub> operating range. The inputs and outputs are high impedance when V<sub>CC</sub> is 0 V. Inputs tolerate voltages up to 5.5 V independent of V<sub>CC</sub> operating range. Outputs tolerate voltages above V<sub>CC</sub> when in the 3–STATE condition.

#### Features

- Space Saving US8 Surface Mount Package
- MicroPak<sup>TM</sup> Pb-Free Leadless Package
- Ultra High Speed: t<sub>PD</sub> 2.6 ns Typ. into 50 pF at 5 V V<sub>CC</sub>
- High Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at  $3.3 \text{ V} \text{ V}_{\text{CC}}$
- Power Down High Impedance Inputs / Outputs
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Outputs are Overvoltage Tolerant in 3-STATE Mode
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

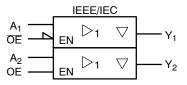
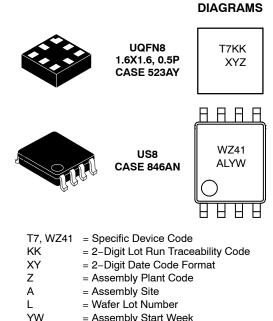


Figure 1. Logic Symbol



#### = Assembly Start Week

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

#### **Connection Diagrams**

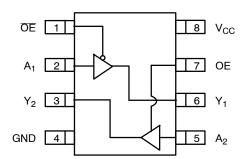
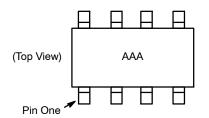


Figure 2. Pin Assignments for US8 (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

#### Figure 3. Pin One Orientation Diagram

# **PIN DESCRIPTIONS**

Pin Names	Description
<del>OE</del> , OE	Enable Inputs for 3-STATE Outputs
A <sub>n</sub>	Inputs
Y <sub>n</sub>	3-STATE Outputs

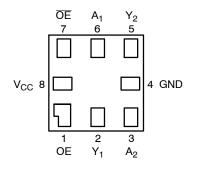


Figure 4. Pad Assignments for MicroPak (Top Thru View)

FUN	СТІ	ON .	ТАВ	LE
	• • • •			

Inputs		Out	put
OE or OE	A <sub>n</sub>	Y <sub>1</sub>	Y <sub>2</sub>
L	L	L	Z
L	Н	Н	Z
Н	L	Z	L
Н	Н	Z	Н

H = HIGH Logic Level L = LOW Logic Level

Z = 3 - STATE

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Paran	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage		-0.5	6.5	V
V <sub>IN</sub>	DC Input Voltage (Note 1)		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
Ι <sub>ΙΚ</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-50	mA
Ι <sub>ΟΚ</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Source / Sink Curren	t	-	±50	mA
I <sub>CC</sub> / I <sub>GND</sub>	DC V <sub>CC</sub> / GND Current		-	±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature under Bias	-	+150	°C	
ΤL	Junction Lead Temperature (Sol	-	+260	°C	
P <sub>D</sub>	Power Dissipation in Still Air	US8 MicroPak-8		500 539	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The input and output negative voltage ratings may be exceeded is the input and output diode current ratings are observed.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol		Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage	Active State	0	V <sub>CC</sub>	V
		3-State	0	5.5	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$V_{CC}$ = 1.8 V, 0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	
		$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	5	
$\theta_{JA}$	Thermal Resistance	US8 MicroPak–8	- -	250 232	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.Unused inputs must be held HIGH or LOW. They may not float.

### DC ELECTICAL CHARACTERISTICS

				T <sub>A</sub> = +25°C			T <sub>A</sub> = −40 to +85°C													
Symbol	Parameter	Conc	litions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit										
V <sub>IH</sub>	HIGH Level Input			1.65 to 1.95	0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	_	V										
	Voltage			2.3 to 5.5	0.7 V <sub>CC</sub>	-	-	0.7 V <sub>CC</sub>	_											
V <sub>IL</sub>	LOW Level Input			1.65 to 1.95	-	-	0.35 V <sub>CC</sub>	-	0.35 V <sub>CC</sub>	V										
	Voltage			2.3 to 5.5	-	-	0.3 V <sub>CC</sub>	-	0.3 V <sub>CC</sub>											
V <sub>OH</sub>	HIGH Level Output	V <sub>IN</sub> = V <sub>IH</sub> or	I <sub>OH</sub> = -100 μA	1.65	1.55	1.65	-	1.55	-	V										
	Voltage	VIL		2.3	2.2	2.3	-	2.2	-											
				3.0	2.9	3.0	-	2.9	-											
				4.5	4.4	4.5	-	4.4	-											
		V <sub>IN</sub> = V <sub>IH</sub> or	I <sub>OH</sub> = -4 mA	1.65	1.29	1.52	-	1.29	-											
		VIL	I <sub>OH</sub> = -8 mA	2.3	1.9	2.15	-	1.9	-											
				I <sub>OH</sub> = -16 mA	3.0	2.4	2.80	-	2.4	-										
															I <sub>OH</sub> = -24 mA	3.0	2.3	2.68	-	2.3
			I <sub>OH</sub> = -32 mA	4.5	3.8	4.20	-	3.8	-											
V <sub>OL</sub>	LOW Level Output	LOW Level Output Voltage	$V_{IN} = V_{IH}$ or	l <sub>OL</sub> = 100 μA	1.65	-	0.0	0.10	-	0.10	V									
	voltage	V <sub>IL</sub>		2.3	-	0.0	0.10	-	0.10											
				3.0	-	0.0	0.10	-	0.10											
				4.5	-	0.0	0.10	-	0.10											
		V <sub>IN</sub> = V <sub>IH</sub> or	I <sub>OL</sub> = 4 mA	1.65	-	0.08	0.24	-	0.24											
		V <sub>IL</sub>	I <sub>OL</sub> = 8 mA	2.3	-	0.10	0.3	-	0.3											
			l <sub>OL</sub> = 16 mA	3.0	-	0.15	0.4	-	0.4											
			I <sub>OL</sub> = 24 mA	3.0	-	0.22	0.55	-	0.55											
			I <sub>OL</sub> = 32 mA	4.5	-	0.22	0.55	-	0.55											
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V, G	ND	1.65 to 5.5	-	-	±0.1	_	±1	μA										
I <sub>OZ</sub>	3–STATE Output Leakage			1.65 to 5.5	-	-	±0.5	_	±5	μA										
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> or V <sub>OUT</sub> =	5.5 V	0.0	-	-	1	_	10	μA										
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5 V, GI	ND	1.65 to 5.5	-	-	1	-	10	μA										

## NOISE CHARACTERISTICS

				T <sub>A</sub> = +25°C		
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Тур	Max	Unit
V <sub>OLP</sub> (Note 3)	Quiet Output Maximum Dynamic V <sub>OL</sub>	C <sub>L</sub> = 50 pF	5.0	-	1.0	V
V <sub>OLV</sub> (Note 3)	Quiet Output Minimum Dynamic V <sub>OL</sub>	C <sub>L</sub> = 50 pF	5.0	-	1.0	V
V <sub>OHV</sub> (Note 3)	Quiet Output Minimum Dynamic V <sub>OH</sub>	C <sub>L</sub> = 50 pF	5.0	-	4.0	V
V <sub>IHD</sub> (Note 3)	Minimum HIGH Level Dynamic Input Voltage	C <sub>L</sub> = 50 pF	5.0	-	3.5	V
V <sub>ILD</sub> (Note 3)	Maximum LOW Level Dynamic Input Voltage	C <sub>L</sub> = 50 pF	5.0	-	1.5	V

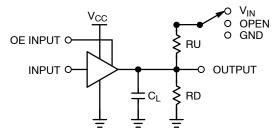
3. Parameter guaranteed by design.

# **AC ELECTRICAL CHARACTERISTICS**

				$T_A = +25^{\circ}C$ $T_A = -4$			T <sub>A</sub> = -40	) to +85°C			
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit		
t <sub>PLH</sub>	Propagation Delay	$C_L = 15  pF$	1.8 ±0.15	-	-	12.0	-	13.0	ns		
t <sub>PHL</sub>	A <sub>n</sub> to Y <sub>n</sub> (Figure 5, 7)	$RD = 1 M\Omega$ $S_1 = OPEN$	2.5 ±0.2	_	-	7.5	-	8.0			
			3.3 ±0.3	-	-	5.2	-	5.5			
			5.0 ±0.5	-	-	4.5	-	4.8			
		C <sub>L</sub> = 50 pF, RD = 500 Ω	3.3 ±0.3	-	-	5.7	-	6.0			
		$S_1 = OPEN$	5.0 ±0.5	-	-	5.0	-	5.3			
toslh	Output to Output Skew	$C_L = 50 \text{ pF},$ RD = 500 $\Omega$ S <sub>1</sub> = Open	3.3 ±0.3	-	-	1.0	-	1.0	ns		
<sup>t</sup> OSHL	(Note 4) (Figure 5, 7)		5.0 ±0.5	-	-	0.8	-	0.8			
t <sub>PZL</sub>	Output Enable Time	$ \begin{array}{llllllllllllllllllllllllllllllllllll$	1.8 ±0.15	-	-	14.0	-	15.0	ns		
t <sub>PZH</sub>	(Figure 5, 7)		$S_1 = GND$ for $t_{PZH}$ $S_1 = V_I$ for $t_{PZL}$	$S_1 = GND$ for $t_{P7H}$	2.5 ±0.2	-	-	8.5	-	9.0	
				3.3 ±0.3	-	-	6.2	-	6.5		
			5.0 ±0.5	-	-	5.5	-	5.8			
t <sub>PLZ</sub>	Output Disable Time	$C_L = 50 \text{ pF}$	1.8 ±0.15	-	-	12.0	-	13.0	ns		
t <sub>PHZ</sub>	(Figure 5, 7)	RD,RU = 500 $\Omega$ S <sub>1</sub> = GND for t <sub>PHZ</sub>	2.5 ±0.2	-	-	8.0	-	8.5			
		$S_1 = V_I \text{ for } t_{PLZ}$ $V_I = 2 \times V_{CC}$	3.3 ±0.3	-	-	5.7	-	6.0			
			5.0 ±0.5	-	-	4.7	-	5.0			
C <sub>IN</sub>	Input Capacitance		0	-	2.5	-	-	-	pF		
C <sub>OUT</sub>	Output Capacitance		5.0	-	4	-	-	-	pF		
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	OE = GND OE = V <sub>CC</sub>	3.3	-	10	-	-	-	pF		
	(Figure 6)	$O\Gamma = ACC$	5.0	-	12	-	-	-			

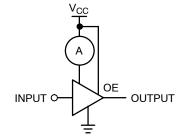
4. Parameter guaranteed by design. t<sub>OSLH</sub> = |t<sub>PLHmax</sub> - t<sub>PLHmin</sub>|; t<sub>OSHL</sub> = |t<sub>PHLmax</sub> - t<sub>PHLmin</sub>|.
5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (see Figure 6) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = (CPD) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).

#### AC Loading and Waveforms



 $C_{L}$  includes load and stray capacitance Input PRR = 1.0 MHz;  $t_{W}$  = 500 ns

#### Figure 5. AC Test Circuit



Input = AC Waveform;  $t_r = t_f = 1.8$  ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I<sub>CCD</sub> Test Circuit

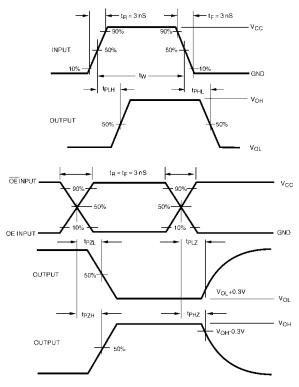


Figure 7. AC Waveforms

#### ORDERING INFORMATION

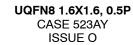
Order Number	Top Mark	Package	Shipping <sup>†</sup>
NC7WZ241K8X	WZ41	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ241K8X-L22236	WZ41	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ241L8X	Τ7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel
NC7WZ241L8X-L22185	Τ7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

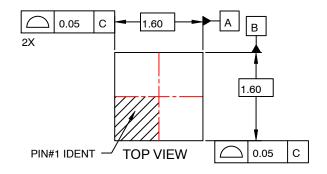
6. Pb-Free package per JEDEC J-STD-020B.

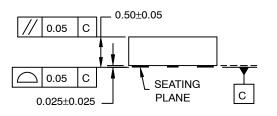
MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.



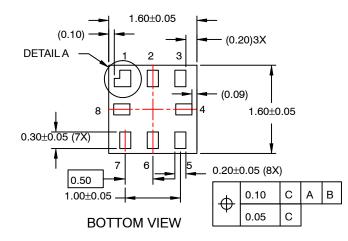


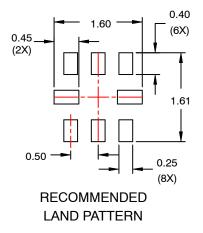
DATE 31 AUG 2016





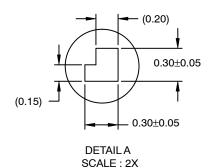
SIDE VIEW





NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



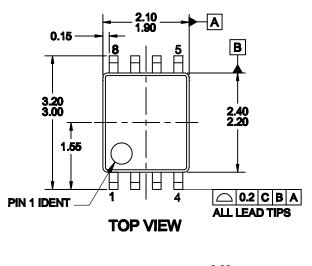
DOCUMENT NUMBER:	98AON13591G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	UQFN8 1.6X1.6, 0.5P		PAGE 1 OF 1			
ON Semiconductor and 🕕 are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding						

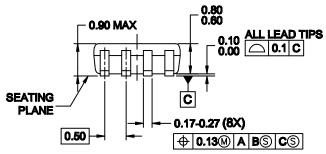
ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclams any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.



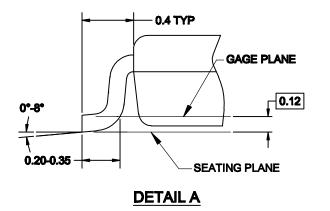
US8 CASE 846AN ISSUE O

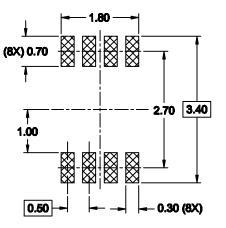
DATE 31 DEC 2016







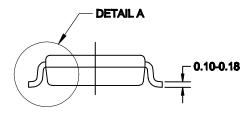




# **RECOMMENDED LAND PATTERN**

# NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187
- **B. DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.



DOCUMENT NUMBER:	98AON13778G Electronic versions are uncontrolled except when accessed directly from the Document Repo Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	US8	PAGE 1 OF 1			
ON Semiconductor reserves the right the suitability of its products for any pa	to make changes without further notice to an articular purpose, nor does ON Semiconducto	stries, LLC dba ON Semiconductor or its subsidiaries in the United States y products herein. ON Semiconductor makes no waranty, representation r assume any liability arising out of the application or use of any product or cidental damages. ON Semiconductor does not convey any license under	or guarantee regarding circuit, and specifically		

© Semiconductor Components Industries, LLC, 2019

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales